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Smart Cards; Smart Secure Platform (SSP); Requirements Specification

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Contents

Intellectual Property Rights	7
Foreword.....	7
Modal verbs terminology.....	7
Introduction	8
1 Scope	9
2 References	9
2.1 Normative references	9
2.2 Informative references.....	11
3 Definition of terms, symbols and abbreviations.....	11
3.1 Terms.....	11
3.2 Symbols.....	13
3.3 Abbreviations	13
4 Abstract (informative).....	14
5 SSP concept description	15
5.1 Introduction	15
5.2 Core features	16
5.3 Security	16
5.4 Electrical characteristics and physical interfaces.....	16
5.4.1 Unlinking electrical characteristics of the SSP from its physical interfaces	16
5.4.2 Operational stages.....	16
6 Background (informative).....	17
6.1 Overview of the use cases	17
6.2 Use Case 1 - Embedded secure element.....	17
6.2.1 Overview	17
6.2.2 Sub use cases	17
6.2.2.1 Use case 1.1 - Embedded secure element, electrical interface.....	17
6.2.2.2 Use case 1.2 - Embedded secure element, physical interface	18
6.2.2.3 Use case 1.3 - Embedded secure element, independence from hardware form factor	18
6.2.2.4 Use case 1.4 - Embedded secure element, protocol interface	18
6.2.3 Interaction with existing features.....	18
6.3 Use case 2 - Securing IoT devices.....	18
6.3.1 Overview	18
6.3.2 Sub use cases	19
6.3.2.1 Use case 2.1 - Management of IoT devices.....	19
6.3.2.2 Use case 2.2 - Constrained terminals for M2M.....	19
6.3.2.3 Use case 2.3 - General power efficiency	19
6.3.3 Interaction with existing features.....	19
6.4 Use case 3 - Storage of large data	19
6.4.1 Overview	19
6.4.2 Sub use cases	19
6.4.2.1 Use case 3.1 - Storage of large configuration data.....	19
6.4.2.2 Use case 3.2 - Storage of identification data.....	19
6.4.2.3 Use case 3.3 - Storage of user data.....	19
6.4.2.4 Use case 3.4 - Storage of emails	19
6.4.3 Interaction with existing features (informative).....	19
6.5 Use case 4 - Security token/HSM.....	20
6.5.1 Overview	20
6.5.2 Sub use cases	20
6.5.2.1 Use case 4.1 - Security for VPN	20
6.5.2.2 Use case 4.2 - Security token for email.....	20
6.5.2.3 Use case 4.3 - Security token for network elements	20
6.5.2.4 Use case 4.4 - Secure boot	20

6.5.3	Interaction with existing features.....	20
6.6	Use case 5 - Multiple applications.....	20
6.6.1	Overview	20
6.6.2	Sub use cases	21
6.6.2.1	Use case 5.1 - Multiple applications active at the same time.....	21
6.6.2.2	Use case 5.2 - Multiple applications from independent stakeholders	21
6.6.3	Interaction with existing features.....	21
6.7	Use case 6 - Optimization for LPWA IoT.....	21
6.7.1	Overview	21
6.8	Use case 7 - Tamper resistant secure hardware component for 3GPP next generation system.....	22
6.8.1	Overview	22
6.8.2	Sub use cases	22
6.8.2.1	Use case 7.1 - Storage and processing of network access credentials.....	22
6.8.2.2	Use case 7.2 - Interworking with non-3GPP systems	22
6.8.3	Interaction with existing features.....	22
6.9	Use case 8 - IMEI protection.....	22
6.10	Use case 9 - Integrated secure element.....	23
6.11	Use case 10 - Evolution of UICC functionality to support 3GPP requirements.....	23
6.11.1	Introduction.....	23
6.11.2	Existing features	23
6.11.2.1	Introduction.....	23
6.11.2.2	File Storage	23
6.11.2.2.1	Introduction	23
6.11.2.2.2	Examples from 3GPP specifications	24
6.11.2.3	Internet of Things.....	25
6.11.2.3.1	Power efficiency.....	25
6.11.2.3.2	Hardware flexibility.....	26
6.11.2.3.3	Electrical Interface and protocols.....	26
6.11.2.4	Toolkit.....	26
6.11.2.4.1	User-related applications	26
6.11.2.4.2	System applications	27
6.11.2.5	Concurrent operation of applications.....	27
6.11.3	Possible new features.....	28
6.11.3.0	General.....	28
6.11.3.1	Storage of data	28
6.11.3.1.1	The ability to provide the ME with storage space	28
6.11.3.1.2	The ability to provide the new secure platform with storage space in the ME	28
6.11.3.2	Extensibility of functionality.....	28
6.11.3.3	Multiple application environment	28
7	SSP Classes overview	28
7.1	Introduction	28
7.2	iSSP: integrated SSP	29
7.3	eSSP: embedded SSP	29
7.4	rSSP: removable SSP	29
8	Requirements applicable for all SSP classes	29
8.1	General	29
8.1.0	Introduction.....	29
8.1.1	General - mandatory requirements.....	30
8.1.2	General - optional requirements.....	30
8.1.3	General - use case specific requirements	30
8.2	Application and file structure	30
8.2.1	SSP applications	30
8.2.1.1	SSP applications - mandatory requirements.....	30
8.2.1.2	SSP applications - optional requirements.....	31
8.2.1.3	SSP applications - use case specific requirements	31
8.2.2	File system	31
8.2.2.1	File system - mandatory requirements	31
8.2.2.2	File system - optional requirements	31
8.2.2.3	File system - class dependent requirements	31
8.2.2.4	File system - use case specific requirements.....	31

8.2.3	SSP application and file system access conditions	32
8.2.3.1	SSP application and file system access conditions - mandatory requirements.....	32
8.2.3.2	SSP application and file system access conditions - optional requirements.....	32
8.2.4	Terminal support for SSP applications	32
8.2.4.1	Terminal support for SSP applications - mandatory requirements.....	32
8.2.4.2	Terminal support for SSP applications - optional requirements.....	32
8.3	Protocols.....	32
8.3.1	Protocols - mandatory requirements	32
8.3.2	Protocols - optional requirements	32
8.3.2.1	SCL network layer requirements.....	32
8.3.2.2	SCL Transport layer requirements	33
8.3.2.3	SCL session layer requirements	33
8.3.2.4	Presentation layer requirements	33
8.3.2.5	Common underlying protocol stack requirements	33
8.3.3	Protocols - class dependent requirements	34
8.3.3.1	Protocols - requirements for SPI.....	34
8.4	Electrical and physical Interface	34
8.4.1	Electrical and physical Interface - mandatory requirements.....	34
8.4.2	Electrical and physical Interface - class dependent requirements.....	34
8.4.2.1	Electrical and physical Interface requirements.....	34
8.4.2.2	Electrical and physical Interface: SPI requirements.....	35
8.4.2.3	Electrical and physical Interface: I2C requirements	35
8.5	Form factor.....	35
8.5.1	Form factor - mandatory requirements	35
8.6	Security	35
8.6.1	Security - mandatory requirements	35
8.6.2	Security - optional requirements	36
8.7	SSP management.....	36
8.7.1	SSP management - mandatory requirements.....	36
8.7.2	SSP management - optional requirements.....	36
8.8	Backwards compatibility.....	36
8.8.1	Backwards compatibility - mandatory requirements.....	36
8.8.2	Backwards compatibility - optional requirements	36
8.9	Primary/secondary platform architecture	37
8.9.1	Primary/secondary platform architecture - class dependent requirements.....	37
8.9.1.1	General.....	37
8.9.1.2	Primary/secondary platform external interfaces and SPB provisioning and management.....	39
8.9.1.2.1	General description.....	39
8.9.1.2.2	Primary/secondary platform external interfaces requirements	40
8.9.1.2.3	SPB metadata requirements.....	41
8.9.1.2.4	SPB provisioning information requirements	42
8.9.1.2.5	Primary/secondary platform PKI requirements	42
8.9.1.3	APIs.....	43
8.9.1.4	Platform applications	43
8.9.1.5	Primary/secondary platform security requirements.....	43
8.9.1.6	Primary/secondary platform core security requirements.....	43
8.9.1.7	Access rights requirements	44
8.9.1.8	Certification requirements.....	44
9	Requirements for iSSP class.....	44
9.1	Introduction	44
9.2	Additional requirements for iSSP.....	44
9.2.0	General Requirements.....	44
9.2.1	Void (Clause is now 8.9.1.3)	45
9.2.2	Filesystem	45
9.2.3	Void (Clause is now 8.9.1.4)	45
9.2.4	Transport protocol	45
9.2.5	Link layer protocol.....	45
9.2.6	Physical and electrical interface.....	45
9.2.7	Form factor	45
9.2.8	Power modes and related timings	45
9.2.9	Security.....	46

9.2.9.1	Generic security requirements.....	46
9.2.9.2	Core platform security requirements.....	47
9.2.9.3	Void (Clause is now 8.9.1.7).....	47
9.2.9.4	Void (Clause is now 8.9.1.8).....	47
9.2.9.5	System on chip security requirements.....	47
9.2.10	Void (Clause is now 8.9.1.1).....	47
9.2.11	Void (Clause is now 8.9.1.2).....	47
9.2.11.1	Void (Clause is now 8.9.1.2.1).....	47
9.2.11.2	Void (Clause is now 8.9.1.2.2).....	47
9.2.11.3	Void (Clause is now 8.9.1.2.3).....	47
9.2.11.4	Void (Clause is now 8.9.1.2.4).....	47
9.2.11.5	Void (Clause is now 8.9.1.2.5).....	47
10	Requirements for eSSP class.....	47
10.1	Introduction.....	47
10.2	Additional requirements for the eSSP class.....	48
10.2.1	Application and file structure.....	48
10.2.1.1	SSP application requirements.....	48
10.2.1.2	File system.....	48
10.2.1.3	SSP application and file system access conditions.....	48
10.2.2	Protocols.....	48
10.2.2.1	Required protocol support.....	48
10.2.3	Electrical and physical Interface.....	48
10.2.3.1	General electrical and physical interface requirements.....	48
10.2.4	Form factor.....	48
10.2.5	Security.....	48
10.2.5.1	Generic security requirements.....	48
10.2.5.2	Certification requirements.....	49
10.2.6	SSP management.....	49
10.2.7	Backwards compatibility.....	49
Annex A (normative):	Telecom bundle requirements.....	50
Annex B (informative):	Change history.....	51
History.....		52

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Introduction

The current specification of the (e)UICC is based on the ISO/IEC 7816 series [1] of specifications for IC-cards. This series of specifications has been developed in the 1980s and was suitable at that point in time but today limits the capabilities that are required by the market. The current (e)UICC specifications also link the form factor to the electrical interface and the logical protocol. This link limits the (e)UICC implementations to specified form factors.

New requirements are emerging, for example inspired by embedded secure elements in terminals that are intended to provide security services or store data securely. Such embedded secure elements may come in different form factors and are intended to be integrated into the terminals architecture and using electrical and physical interfaces other than those used by the (e)UICC. Such secure elements could also provide the capability to store large amount of data to be protected which requires new and more efficient ways to store and manage data.

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1 Scope

The present document defines the use cases and requirements for the definition of the interfaces and protocols for interfacing with a secure element. This secure element is called Smart Secure Platform (SSP).

2 References

2.1 Normative references

References are either specific (identified by date of publication and/or edition number or version number) or non-specific. For specific references, only the cited version applies. For non-specific references, the latest version of the reference document (including any amendments) applies.

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The following referenced documents are necessary for the application of the present document.

- [1] ISO/IEC 7816 (all parts): "Identification cards -- Integrated circuit cards".
- [2] ETSI TS 102 221: "Smart Cards; UICC-Terminal interface; Physical and logical characteristics".
- [3] ETSI TS 102 671: "Smart Cards; Machine to Machine UICC; Physical and logical characteristics".
- [4] ETSI TS 102 613: "Smart Cards; UICC - Contactless Front-end (CLF) Interface; Part 1: Physical and data link layer characteristics".
- [5] SOG-IS: "Protection Profiles".

NOTE: Available at https://www.sogis.eu/uk/pp_en.html.

- [6] ETSI TS 102 622: "Smart Cards; UICC - Contactless Front-end (CLF) Interface; Host Controller Interface (HCI)".
- [7] ISO/IEC 7816-3: "Identification cards -- Integrated circuit cards -- Part 3: Cards with contacts - Electrical interface and transmission protocols".
- [8] ISO/IEC 7816-4: "Identification cards -- Integrated circuit cards -- Part 4: Organization, security and commands for interchange".
- [9] ETSI TS 102 600: "Smart Cards; UICC-Terminal interface; Characteristics of the USB interface".
- [10] ETSI TS 133 501: "5G; Security architecture and procedures for 5G System (3GPP TS 33.501 Release 15)".
- [11] Security IC Platform BSI Protection Profile 2014 with Augmentation Packages.

NOTE: Available at https://www.commoncriteriaportal.org/files/ppfiles/pp0084b_pdf.pdf.

- [12] Application of Attack Potential to Smartcards (V2.9) (01-2013).

NOTE: Available at <https://www.sogis.eu/documents/cc/domains/sc/JIL-Application-of-Attack-Potential-to-Smartcards-v2-9.pdf>.

- [13] "GlobalPlatform Card Technology; Open Firmware Loader for Tamper Resistant Element".

- [14] ETSI TS 102 223: "Smart Cards; Card Application Toolkit (CAT)".
- [15] ETSI TS 131 102: "Universal Mobile Telecommunications System (UMTS); LTE; Characteristics of the Universal Subscriber Identity Module (USIM) application (3GPP TS 31.102)".
- [16] Recommendation ITU-T X.680: "OSI networking and system aspects - Abstract Syntax Notation One (ASN.1)".
- [17] IETF RFC 7252: "The Constrained Application Protocol (CoAP)".
- [18] ETSI TS 102 241: "Smart Cards; UICC Application Programming Interface (UICC API) for Java Card™".
- [19] ETSI TS 102 705: "Smart Cards; UICC Application Programming Interface for Java Card™ for Contactless Applications".
- [20] ETSI TS 124 383: "LTE; Mission Critical Push To Talk (MCPTT) Management Object (MO) (3GPP TS 24.383)".
- [21] ETSI TS 124 334: "Universal Mobile Telecommunications System (UMTS); LTE; Proximity-services (ProSe) User Equipment (UE) to ProSe function protocol aspects; Stage 3 (3GPP TS 24.334)".
- [22] ETSI TS 132 277: "Universal Mobile Telecommunications System (UMTS); LTE; Telecommunication management; Charging management; Proximity-based Services (ProSe) charging (3GPP TS 32.277)".
- [23] ETSI TS 124 333: "Universal Mobile Telecommunications System (UMTS); LTE; Proximity-services (ProSe) Management Objects (MO) (3GPP TS 24.333)".
- [24] ETSI TS 124 385: "LTE; V2X services Management Object (MO) (3GPP TS 24.385)".
- [25] ETSI TS 102 225: "Smart Cards; Secured packet structure for UICC based applications".
- [26] ETSI TS 102 226: "Smart Cards; Remote APDU structure for UICC based applications".
- [27] IETF RFC 4122: "A Universally Unique Identifier (UUID) URN Namespace".
- [28] ETSI TS 134 108: "Universal Mobile Telecommunications System (UMTS); LTE; Common test environments for User Equipment (UE); Conformance testing (3GPP TS 34.108)".
- [29] GSMA TS.37 (V4.0) (06/2018): "Requirements for Multi SIM Devices".
- [30] IETF RFC 5280: "Internet X.509 Public Key Infrastructure Certificate and Certificate Revocation List (CRL) Profile".
- [31] ETSI TS 123 003: "Digital cellular telecommunications system (Phase 2+) (GSM); Universal Mobile Telecommunications System (UMTS); Numbering, addressing and identification (3GPP TS 23.003)".
- [32] GSMA SGP.02 (V3.2) (06/2017): "Remote Provisioning Architecture for Embedded UICC Technical Specification".
- [33] GSMA SGP.22 (V2.2.1) (12/2018): "RSP Technical Specification".

2.2 Informative references

References are either specific (identified by date of publication and/or edition number or version number) or non-specific. For specific references, only the cited version applies. For non-specific references, the latest version of the reference document (including any amendments) applies.

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- [i.1] Recommendation ITU-T E.212: "The international identification plan for public networks and subscriptions".
- [i.2] ETSI TR 102 216: "Smart cards; Vocabulary for Smart Card Platform specifications".
- [i.3] ETSI TR 131 970: "Universal Mobile Telecommunications System (UMTS); LTE; 5G; UICC power optimisation for Machine-Type Communication (MTC) (3GPP TR 31.970)".

3 Definition of terms, symbols and abbreviations

3.1 Terms

For the purposes of the present document, the terms given in ETSI TR 102 216 [i.2] and the following apply:

Certificate Issue (CI): root CA which issues digital certificates to the certified entities in the SSP ecosystem

embedded UICC: UICC which is not easily accessible or replaceable, that is not intended to be removed or replaced in the terminal, and enables the secure changing of subscriptions

family identifier: identifier specified by GP OFL [13] that can be used to categorize secondary platform bundles

forward compliance: capability to support future releases of a specification

image: generic data format encapsulating a secondary platform bundle version and its cryptographic data to be used by the SPBL

internal Non Volatile Memory (iNVM): non volatile memory physically located inside an SSP

Local Bundle Assistant (LBA): entity in the terminal managing the secondary platform bundles

Mobile Network Operator (MNO): entity providing communication services to its customers through mobile networks

Network Access Application (NAA): application residing on an eUICC that provides authorization to access an Recommendation ITU-T E.212 network [i.1]

EXAMPLE: A USIM application.

Network Access Credentials (NAC): data required to authenticate to an Recommendation ITU-T E.212 [i.1] Network

NOTE: Network access credentials may include data such as Ki/K, and IMSI stored within a NAA.

non-shareable memory regions: memory space that is declared by, and accessed by a single program

primary platform: hardware platform along with a low-level operating system managing the exceptions, the hardware platform resources and their accesses. The primary platform is use case independent and technology dependent

remote Non Volatile Memory (rNVM): non volatile memory physically located outside an iSSP

secondary platform: software platform using the primary platform interface and containing the high-level operating system on top of which the SSP applications are running

Secondary Platform Bundle (SPB): secondary platform along with its SSP applications

Secondary Platform Bundle Loader (SPBL): application, requiring system specific privileges, used to load a secondary platform bundle

Secondary Platform Bundle Loader agent: part of the local bundle assistant managing the communication with the secondary platform bundle manager and the transfer of the image to secondary platform bundle loader on the SSP

Secondary Platform Bundle Manager (SPBM): entity which builds an image on behalf of the service provider this image belongs to and securely delivers it to the SPBL on the target iSSP through the SPBL agent

Secondary Platform Bundle metadata: information belonging to a secondary platform bundle used for the purpose of management of the SPB

Secure Element (SE): tamper-resistant dedicated platform, consisting of hardware and software, capable of securely hosting applications and their confidential and cryptographic data and providing a secure application execution environment

Service Provider (SP): entity defining the requirements of a secondary platform bundle

SSP application: application running on the top of an SSP OS (e.g. USIM)

SSP class: configuration of the SSP in accordance with a business requirement

SSP information: information of the primary platform and the SPBL which is used for the eligibility checking of the iSSP by the SPB manager

SSP maker: entity which manufactures the SSP

SSP OS: operating system compliant with the SSP specifications

System on Chip (SoC): system on chip is an integrated circuit that contains all the required circuitry and components of an electronic system on a single chip

telecom bundle: secondary platform bundle which contains or is intended to contain at least one 3GPP NAA. For example, a secondary platform bundle providing functions as defined in the GSMA remote SIM provisioning specifications GSMA SGP.02 [32], GSMA SGP.22 [33] or 3GPP specification ETSI TS 131 102 [15] would be classified as a telecom bundle

telecom bundle class: indicates the sort of a telecom bundle (e.g. operational, provisioning, test, eSIM), with which the iSSP and the terminal can handle the telecom bundle appropriately

telecom bundle concurrency capability: parameter which is set on the iSSP, indicating the number of distinct concurrent 3GPP/3GPP2 network registrations based on different subscriber identifier, supported by the cellular baseband capability inside the SoC containing the iSSP

EXAMPLE: "1" for a baseband supporting single-SIM, and "2" for a baseband supporting dual-SIM (either dual-SIM dual-active or dual-SIM dual-standby).

telecom family identifier: family identifier having a reserved value, used to class a secondary platform bundle as a telecom bundle

telecommunications Service Provider: MNO, or party trusted by the MNO acting on behalf of the MNO, which provides services to the subscriber

terminal information: information of the terminal which is used for the eligibility checking of the terminal by the SPB Manager

test telecom bundle: telecom bundle containing a 3GPP NAA which is intended to access a 3GPP test network (e.g. a network compliant with ETSI TS 134 108 [28])

3.2 Symbols

Void.

3.3 Abbreviations

For the purposes of the present document, the following abbreviations apply:

AID	Application Identifier
AKA	Authentication and Key Agreement
APDU	Application Protocol Data Unit
API	Application Programming Interface
APN	Access Point Name
ASN	Abstract Syntax Notation
CA	Certificate Authority
CAT	Card Application Toolkit
CI	Certificate Issuer
CLK	Clock
CPU	Central Processing Unit
CS	Circuit Switched
DNS	Domain Name System
DPA	Differential Power Analysis
DTLS	Datagram Transport Layer Security
EAP	Extensible Authentication Protocol
EF	Elementary File
EMA	Electromagnetic Attacks
EPC	Evolved Packet Core
eSSP	embedded SSP
eUICC	embedded UICC
FFS	For Further Study
GSMA	GSM Association
HCI	Host Controller Interface
HPSIM	Hosting Party Subscription Identity Module
HSM	Hardware Security Module
IMEI	International Mobile Subscriber Identity
IMSI	International Mobile Subscriber Identity
iNVM	internal Non-Volatile Memory
IP	Internet Protocol
ISIM	IP Multimedia Services Identity Module
ISO	International Organisation for Standardization
iSSP	integrated SSP/M2M Machine to Machine (communication)
JIL	Joint Interpretation Library
LBA	Local Bundle Assistant
LPWA	Low Power Wide Area
MCPTT	Mission Critical Push ToTalk
ME	Mobile Equipment
MNO	Mobile Network Operator
MTC	Machine-Type Communication
MTU	Maximum Transport Unit
NAA	Network Access Application
NAC	Network Access Credentials
NIST	National Institute of Standards and Technology
NVM	Non Volatile Memory
OFL	Open Firmware Loader
OS	Operating System
OSI	Open Systems Interconnection
PIN	Personal Identification Number
PKI	Public Key Infrastructure
PPI	Primary Platform Interface
RFM	Remote File Management
rNVM	remote Non-Volatile Memory